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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HAGIWARA, et al.

Serial No.: 09/482,859

Filed: January 14, 2000

For: PATTERN FORMING PROCESS USING
PHOTOSENSITIVE RESIN COMPOUND

Group: 1752

Examiner: J. Chu

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

January 18, 2002

Sir:

In response to the Office Action mailed October 18, 2001, please amend
the above-identified application as follows:

IN THE CLAIMS

Please amend the claims presently in the application as follows:

25. (Twice Amended) A photosensitive resin composition which
comprises (1) a polyimide precursor formed from an oxydiphthalic acid or acid
anhydride thereof with a diamine, (2) an addition-polymerizable compound, and